# **S2155**

## (ANSI:CEM-3) Halogen-Free CEM-3 Copper Clad Laminate

### 特点

- 不含卤素、锑、红磷等有毒成分。 燃烧时的发烟量和气味少,不产生剧毒气体和不残留有毒成
- r。 机械加工性优秀,对钻孔、冲模磨损小。 PCB加工工艺与普通CEM-3相同。
- 符合IPC-4101标准及JPCA标准。

### **FEATURES**

- Toxic constituents free such as halogen, antimony and red phosphorus.
- Low emitting of smoke and odors in combustion, fewer emitting of poisonous gas and no residue of harmful constituents.
- Significant mechanical workability, lower wearing of bits and
- Same processability of PCB as conventional CEM-3.
- Conform to IPC-4101 standard & JPCA standard.

## 应用领域

家电、OA设备、电源基板、仪器仪 表、游戏机等。

### **APPLICATIONS**

Appliance, OA equipment, power base board, apparatus and instrument, game machine, etc.

# GENERAL PROPERTIES

Test Item		Treatment Condition	Unit	Property Data	
				SPEC	Typical Value
Tg		DSC		-	128
Flammability		C-48/23/50	_	V-0	V-0
		E-24/125			
Volume Resistivity		C-96/35/90	M -cm	10 <sup>6</sup>	2.8 × 10 <sup>8</sup>
		E-24/125	IVI -CITI	10 <sup>3</sup>	$1.6 \times 10^{7}$
Surface Resistance		C-96/35/90	М	10 <sup>4</sup>	3.2 × 10 <sup>6</sup>
		E-24/125	IVI	10 <sup>3</sup>	2.7 × 10 <sup>6</sup>
Arc Resistance		D-48/50+D-0.5/23	S	60	138
Dielectric	Breakdown	D-48/50+D-0.5/23	KV	40	45+kv NB
Dielectric Constant (1MHz)		C-24/23/50	-	5.4	4.8
Dissipation Factor (1MHz)		C-24/23/50	-	0.035	0.010
Thermal Stress	Unetched Etched	260 ,20s	-	No delamination	288 /20s No delamination
Peel	1oz	260 ,10s	N/mm	1.05	1.40
Strength	Cu. Foil	105	IN/IIIIII	0.70	1.40
Flexural	LW	A	MPa	276	356
Strength CW		] ^	IVIFA	186	301
Water Absorption		D-24/23	%	0.35	0.10
CTE.	Before Tg	TMA	μm/m	-	47
z-axis	After Tg	TIVIA	μm/m	-	316

Specimen Thickness:1.6mm

Explanations:

C = Humidity conditioning; D = Immersion conditioning in distilled water;

E = Temperature conditioning.

The figures following the letter symbols indicate with the first digit the duration of the preconditioning in hours, with the second digit the preconditioning temperature in and with the third digit the relative humidity.

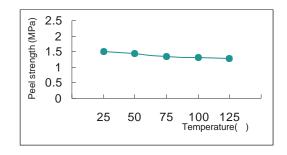
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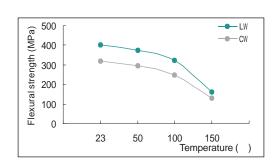
### ■ Water absorption at pressure cooker

#### 0.9 0.8 0.7 8 0.6 0.5 0.5 0.2 0.1 0 0.5 1 2 3 4 5 Condition time (hr)

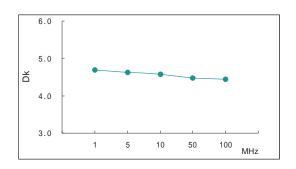
### Peel strength



### ■ Flexural strength



#### Dielectric constant



### **PURCHASING INFORMATION**

Thickness	Copper foil	Standard Size				
0.6mm	18 µ m	1,020 × 1,220mm (40 × 48 ) 915 × 1,220mm (36 × 48 )				
to 3.2mm	to 105 µ m	1,070 × 1,220mm (42 × 48 )				

<sup>\*</sup> Other sheet size and thickness could be available upon request.

#### **HALOGEN CONTENT TEST**

★ JPCA-ES-01-1999 Standard "Test method of halogen-free materials"

Halogen	JPCA Standard	S2155
CI	0.09%	0.04%
Br	0.09%	0.00%